54AC16374, 74AC16374 16-BIT EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

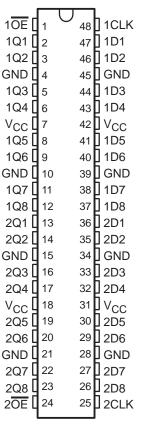
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- Members of the Texas Instruments Widebus™ Family
- 3-State True Outputs
- Full Parallel Access for Loading
- Flow-Through Architecture Optimizes
 PCB Layout
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1-μm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings

description

The 'AC16374 are 16-bit edge-triggered D-type flip-flops with 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

54AC16374... WD PACKAGE 74AC16374... DL PACKAGE (TOP VIEW)



The 'AC16374 can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock (CLK) input, the Q outputs of the flip-flop take on the logic levels set up at the data (D) inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly.

OE does not affect the internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The 74AC16374 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54AC16374 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74AC16374 is characterized for operation from –40°C to 85°C.



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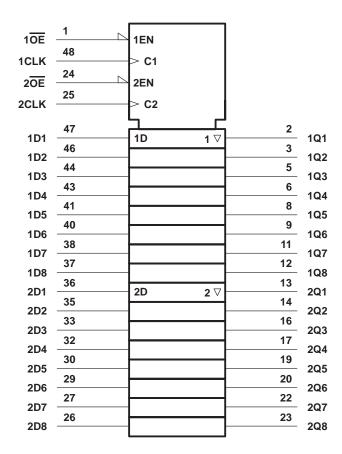


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FUNCTION TABLE

	INPUTS		OUTPUT
OE	CLK	D	Q
L	1	Н	Н
L	\uparrow	L	L
L	X	Χ	Q ₀
L	\downarrow	Χ	Q_0
Н	X	Χ	Z

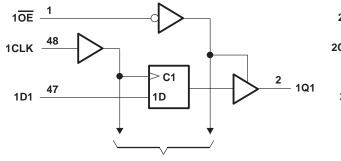
logic symbol†



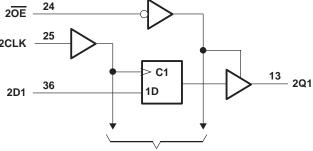
[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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logic diagram (positive logic)



To Seven Other Channels



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)—($0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, V _O (see Note 1)($0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V _{CC} or GND	±400 mA
Maximum power package dissipation at $T_A = 55^{\circ}C$ (in still air)(see Note 2): DL package	1.2 W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.



54AC16374, 74AC16374 16-BIT EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

SCAS123B - MARCH 1990 - REVISED APRIL 1996

recommended operating conditions (see Note 3)

			54AC16374			74	AC1637	4	LINUT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		3	5	5.5	3	5	5.5	V
		V _{CC} = 3 V	2.1			2.1			
V_{IH}	High-level input voltage	V _{CC} = 4.5 V	3.15			3.15			V
		V _{CC} = 5.5 V	3.85			3.85			
		VCC = 3 V			0.9			0.9	
V_{IL}	Low-level input voltage	V _{CC} = 4.5 V			1.35			1.35	V
		V _{CC} = 5.5 V		14	1.65			1.65	
٧ _I	Input voltage		0	Q	Vcc	0		Vcc	V
۷o	Output voltage		0	Ó	Vcc	0		Vcc	V
		VCC = 3 V	4	3	-4			-4	
loh	High-level output current	V _{CC} = 4.5 V	20		-24			-24	mA
		V _{CC} = 5.5 V			-24			-24	
		V _{CC} = 3 V			12			12	
loL	Low-level output current	V _{CC} = 4.5 V			24			24	mA
		V _{CC} = 5.5 V			24			24	
Δt/Δν	Input transition rise or fall rate		0		10	0		10	ns/V
T _A	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER	TEST CONDITIONS	V	T,	_Δ = 25°C	;	54AC1	6374	74AC1	6374	UNIT
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
		3 V	2.9			2.9		2.9		
	I _{OH} = -50 μA	4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
Voн	$I_{OH} = -4 \text{ mA}$	3 V	2.58			2.48		2.48		V
	4.5 V 3.94	3.8		3.8						
	I _{OL} = -24 mA	5.5 V	4.94			4.8		4.8		
	I _{OH} = -75 mA [†]	5.5 V				3.85		3.85		
		3 V			0.1		0.1		0.1	
	I _{OL} = 50 μA	4.5 V			0.1		0.1		0.1	
		5.5 V			0.1	, <	0.1		0.1	
VOL	I _{OL} = 12 mA	3 V			0.36	,0	0.44		0.44	V
	I _{OL} = 24 mA	4.5 V			0.36	9	0.44		0.44	
	10L - 24 111A	5.5 V			0.36	Q.	0.44		0.44	
	I _{OL} = 75 mA [†]	5.5 V				,	1.65		1.65	
lį	V _I = V _{CC} or GND	5.5 V			±0.1		±1		±1	μΑ
loz	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5		±5	μΑ
l _{CC}	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		80		80	μΑ
C _i	$V_I = V_{CC}$ or GND	5 V		3						pF
Co	$V_O = V_{CC}$ or GND	5 V		11						pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.



SCAS123B - MARCH 1990 - REVISED APRIL 1996

timing requirements over recommended operating free-air temperature range V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

			$T_A = 2$	25°C	54AC1	6374	74AC1	6374	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency		0	60	0	60	0	60	MHz
t _W	Pulse duration	CLK high or low	8.3		8.3	10,00	8.3		ns
t _{su}	Setup time, data before CLK↑		7.5		7.5	110	7.5		ns
th	Hold time, data after CLK↑		0		0		0		ns

timing requirements over recommended operating free-air temperature range V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

			T _A = 2	25°C	54AC1	6374	74AC1	6374	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency		0	100	0	100	0	100	MHz
t _W	Pulse duration	CLK high or low	5		5	10,01	5		ns
t _{su}	Setup time, data before CLK↑		5		5	110	5		ns
t _h	Hold time, data after CLK↑		0		0		0		ns

switching characteristics over recommended operating free-air temperature range V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

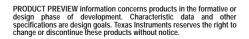
PARAMETER	FROM	то	T,	_Δ = 25°C	;	54AC1	6374	74AC1	6374	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
f _{max}			60			60	7	60		MHz
^t PLH	CLK	0	4.9	12.2	15	4.9	17	4.9	17	ns
t _{PHL}	CLK	Q	4.8	11.9	14.3	4.8	15.7	4.8	15.7	115
^t PZH	ŌĒ	Q	4.3	11.9	14.7	4.3	16.8	4.3	16.8	20
tPZL	OE	Q	5.3	15.5	18.7	5.3	21.2	5.3	21.2	ns
^t PHZ	ŌĒ	0	4	7.3	9	64	9.8	4	9.8	ne
t _{PLZ}] UE	Q	3.8	7.1	8.8	3.8	9.4	3.8	9.4	ns

switching characteristics over recommended operating free-air temperature range V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	Т,	_Δ = 25°C	;	54AC1	6374	74AC1	6374	
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
f _{max}			100			100	4	100		MHz
^t PLH	CLK	Q	3.8	7.6	9.5	3.8	10.8	3.8	10.8	ns
^t PHL	CLK	Q	3.8	7.6	9.5	3.8	10.6	3.8	10.6	115
^t PZH	ŌĒ	Q	3.2	7.2	9	3.2	10.2	3.2	10.2	20
tPZL	OE	ų ,	3.8	8.7	10.7	3.8	12.1	3.8	12.1	ns
^t PHZ	ŌĒ	Q	3.7	6	7.5	3.7	8.2	3.7	8.2	ns
t _{PLZ}) UE		3.5	5.8	7.3	3.5	7.9	3.5	7.9	115

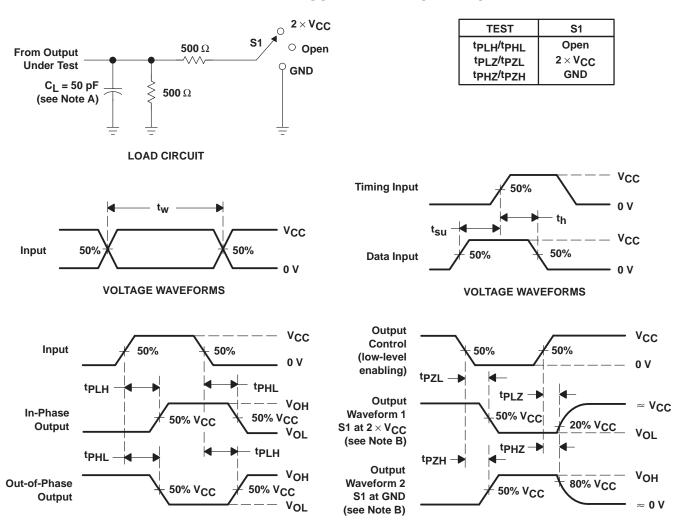
operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CO	TYP	UNIT		
<u> </u>	Dower discipation conscitance per flip flep	Outputs enabled	C ₁ = 50 pF,	f = 1 MHz	49	pF
Cpd	Power dissipation capacitance per flip-flop	Outputs disabled	CL = 50 pr,	I = I IVIDZ	32	þг





PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

VOLTAGE WAVEFORMS

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f = 3$ ns. $t_f = 3$ ns.

VOLTAGE WAVEFORMS

D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGE OPTION ADDENDUM

10-Dec-2020

PACKAGING INFORMATION

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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
74AC16374DL	ACTIVE	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC16374	Samples
74AC16374DLR	ACTIVE	SSOP	DL	48	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC16374	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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10-Dec-2020

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

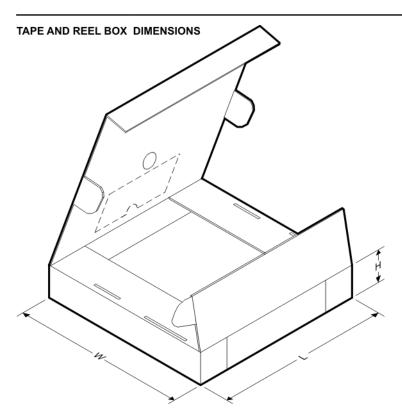
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74AC16374DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

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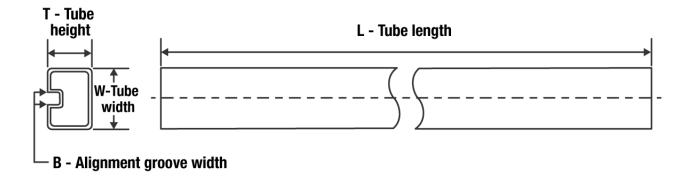
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74AC16374DLR	SSOP	DL	48	1000	367.0	367.0	55.0

PACKAGE MATERIALS INFORMATION

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TUBE

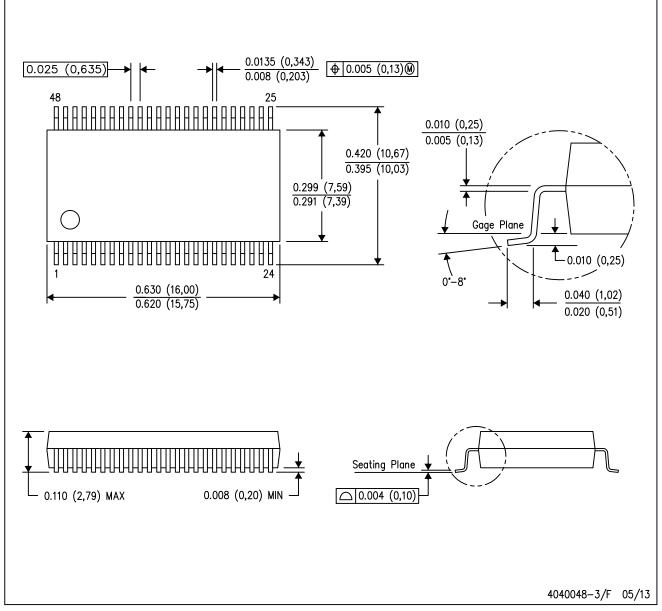


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
74AC16374DL	DL	SSOP	48	25	473.7	14.24	5110	7.87

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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